

TITLE OF INVENTION: SEMICONDUCTOR PACKAGE AND METHOD FOR MAKING THE SAME

Abstract

A semiconductor package comprises: a substrate comprising a substrate interconnection structure; a base semiconductor die comprising a plurality of through vias at a periphery of the base semiconductor die and extending between a top surface and a bottom surface of the base semiconductor die, each electrically coupled to the substrate; at least one first semiconductor component disposed beside the base semiconductor die, wherein the base semiconductor die is electrically connected to the at least one first semiconductor component via the substrate interconnection structure; an encapsulant layer for encapsulating the at least one first semiconductor component and the base semiconductor die but exposing the top surface of the base semiconductor die; and at least one second semiconductor component disposed on the top surface of the base semiconductor die and the encapsulant layer, and electrically coupled to the substrate through at least one of the plurality of through vias.

[Fig. 1A]